B. Flip-Chip Technology

B4.5 References

[B1] Flipped out over flip chip, IPC Review, January 1998, 1,15-16.
[B1] G. Schiebel, "A very promising technology – COB and flip chip processing with flexible SMD equipment – part I", EPP Printed Circuit Board, August 1997, 31-33.
[B1] D. Patterson, P. Elenius and J. Leal, "A Comparative Analysis – Solder deposition process and assembly wafer bumping – part II", EPP Printed Circuit Board, May 1998, 30 – 36.
[B1] C. Bash and R. Blanco, "Improving Heat Transfer from a Flip-Chip Package," Hewlett-Packard Journal, Aug. 1997, 121-5.
[B1] Flip Chip Technologies, ed. John H. Lau, McGraw-Hill, 1995, p. 158-171.
[B1] T-Y. Lee and M. Mahalingam, "Thermal Limits of Flip Chip Package – Experimentally Validated, CFD Supported Case Studies," IEEE Trans. on Components, Packaging, and Manufacturing Techonolgy – Part B, Vol 20, No. 1, February 1997, 94 – 103.
[B1] D. Patterson, P. Elenius and J. Leal, "A Comparative Analysis – Solder deposition process and assembly wafer bumping – part I", EPP Printed Circuit Board, March 1998, 40 – 41.
[B1] H. Ghouz and E. EL-Sharawy, "An Accurate Equivalent Circuit Model of Flip Chip and Via Interconnects",IEEE Transactions on Microwave theory and techniques, vol. 44,no. 12, pp. 2543-2554, Dec 1996.
[B1] H. Hashemi and D. Herrell, "Power Distribution Fidelity of Wirebond Compared to Flip Chip Devices in Grid Array Packages", IEEE Transactions on components, packaging, and manufacturing technology – Part B, vol. 20, no. 3, pp. 272-278, Aug. 1997.
[B1] Flip Chip Technologies, ed. John H. Lau, McGraw-Hill, 1995, p.137.
[B1] S.F. Popelar 1998.
[B1] John H. Lau and Yi-Hsin Pao, Solder Joint Reliability of BGA, CSP, Flip Chip, and Fine Pitch SMT Assemblies, McGraw-Hill, 1997, 408 pages.
[B1] J-STD-012 Implementation of Flip Chip and Chip Scale Technology - Chair, Ray Prasad Concultancy Group, Jan 1996.
[B1] J.-P. Clech, "Solder Reliability Solutions: A PC-based Design-for-reliability Tool", Soldering & Surface Mount Technology, no. 26, pp. 45-54 July 1997.
[B1] Flip Chip Technologies, ed. John H. Lau, McGraw-Hill, 1995, p. 137
[B1] Multichip Module Technologies and Alternatives - The Basics, ed. Daryl Ann Doane and Paul D. Franzon, Van Nostrand Reinhold,1993, page 632.
[B1] John H. Lau , Flip Chip Technologies, McGraw-Hill, 1995, p.19.
[B1] John H. Lau , Flip Chip Technologies, McGraw-Hill, 1995, p.508.
[B1] John H. Lau , Flip Chip Technologies, McGraw-Hill, 1995, p. 526, 532-535.
[B1] http://www.national.com/appinfo/milaero/pages/0,1609,141,00.htm
[B1] J. Eldring, E. Zakel and H. Reichl, " Flip-Chip Attach of Silicon and GaAs Fine Pitch Devices as well as Inner Lead TAB Attach Using Using Ball-bump Technology", Hybrid Circuits No. 34, May 1994.
[B1] H. Yatsuda, T. Horishima, T. Eimura an T. Ooiwa, Miniaturized SAW Filters Using a Flip-Chip Technique, IEEE Transactions on Ultrasonics, Ferroelectrics, and Frequency Control, Vol. 43, N0 1, January 1996, p. 125.
[B1] H. Yatsuda and T. Eimura," Interconnection of Gold-Gold Thermosonic Face-Down Bonding, ISHM Nordic 1996, p. 154.
[B1] O. Rusanen and J. Lenkkeri, "Reliability Issues of Replacing Solder with Conductive Adhesives in Power Modules", IEEE Transactions on components, packaging, and manufacturing technology – Part B, voil 18, no2, May 1996, p. 320-325.
[B1] A. Tolvgård, Jens Malmodin, J. Liu and Zonghe Lai, " A Reliable and Environmentally Friendly Packaging Technology – Flip Chip Joining Using Anisotropically Conductive Adhesive", ". Proceedings of the 3rd International Conference on Adhesive Joining and Coating Technology in Electronics Manufacturing, September 28-30, 1998, Binghamton, New York, p. 19-26.
[B1] R.Sihlbom, M. Dernevik, Zonghe Lai, P. Starski and J. Liu, "Conductive Adhesives for High-Frequency Applications", Proceedings of the first IEEE International Symposium on Polymeric Electronics Packaging, October 26-30, 1997, Norrköping, Sweden, p. 123-130.

[B1] R. Aschenbrenner, R. Miessner and H. Reichl, “Adhesive Flip Chip Bonding on Flexible Substrates”, Proceedings of the first IEEE International Symposium on Polymeric Electronics Packaging, October 26-30, 1997, Norrköping, Sweden, p. 86-93.
[B1] J. Lenkkeri and J. Vähäkangas, “Reliability Testing and Stress Stain Estimations of Flip-Chip Joints made by Stud-Bump-Bonding Technique”. Proceedings of the 3rd International Conference on Adhesive Joining and Coating Technology in Electronics Manufacturing, September 28-30, 1998, Binghamton, New York, p. 305-311.